

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6802xxxx4R-G
Typical Mass: 4 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.394	Silicon	98400	7440-21-3
	-	Arsenic	9	7440-38-2
Lead pad	1.220	Nickel	305000	7440-02-0
	0.056	Silver	14000	7440-22-4
	0.012	Gold	3000	7440-57-5
Die attach	0.025	Epoxy Resin	6200	—
	0.021	Aluminum Oxide	5400	1344-28-1
	0.000	Silica	100	—
Bonding wire	0.059	Gold	14800	7440-57-5
Resin	1.936	Silica	484100	60676-86-0
	0.111	Epoxy Resin	27600	—
	0.099	Phenol Resin	24900	—
	0.066	Metal Hydroxide	16600	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."